

Sigma W8

Automatic wafer bond tester



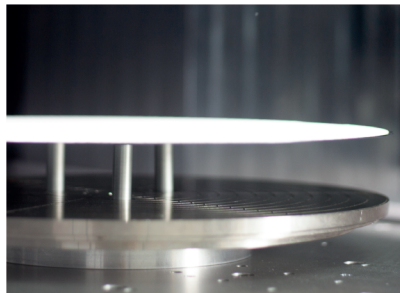
Bond tester for 8 inch wafers

- Bond tester for wafers or at wafer level 2" - 8" (up to 200 mm)
- Fully automatic wafer bond tester
- X/Y stages X: 370 mm, Y: 370 mm
- Force range from 1 gf - 10 kgf
- Bump pitch down to 50 μ m



Full automation

All Sigma bond testers are modular by design and come with game-changing automation capabilities for automatic loading, testing and analyzing. The Revolving Measurement Unit (RMU) houses up to 6 sensors that enable continuous testing. The software includes vision and deep learning technology to eliminate human errors.



Wafer loader

Integrate the Sigma W8 with an independent wafer (un)loader for hands-free bond testing. The wafer handler automatically loads, aligns, and transfers the wafers from the cassette onto the bond tester.

Intelligent lift pins

The system gently secures flat and warped wafers with the soft, flexible tips on the PID controlled wafer lift pins.



Upgrade to Sigma W12

The Sigma W8 is upgradeable to the market-leading Sigma W12 bond tester, which can test wafers up to 12 inches (300 mm) fully automatically. The Sigma W12 comes with a 600 mm X stage to test bumps down to 20 μ m. The upgrade possibility makes the Sigma W8 a future-proof investment.